



DATA SHEET

SB820D~SB8150D

D²PAK SURFACE MOUNTSCHOTTKY BARRIER RECTIFIER

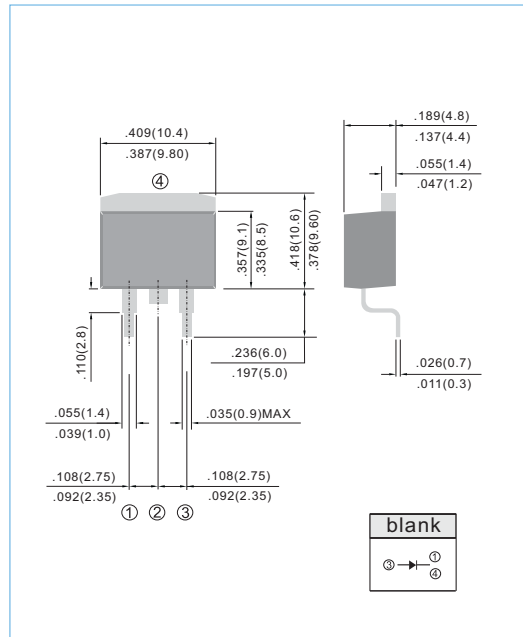
VOLTAGE	20 to 150 Volts	CURRENT	8 Ampere	TO-263 / D²PAK	Unit: inch (mm)
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FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-O utilizing Flame Retardant Epoxy Molding Compound.
- Exceeds environmental standards of MIL-S-19500/228
- Low power loss, high efficiency.
- Low forward voltage, high current capability
- High surge capacity.
- For use in low voltage,high frequency inverters free wheeling , and polarity protection applications.
- Both normal and Pb free product are available :
Normal : 80~95% Sn, 5~20% Pb
Pb free: 99% Sn above

MECHANICALDATA

Case: TO-263/D²PAK molded plastic package
 Terminals: Lead solderable per MIL-STD-202G, Method 208
 Polarity: As marked.
 Mounting Position: Any
 Weight: 0.06 ounces, 1.7 grams.



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.
 For capacitive load, derate current by 20%

PARAMETER	SYMBOL	SB820D	SB830D	SB840D	SB850D	SB860D	SB880D	SB8100D	SB8150D	UNITS	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	20	30	40	50	60	80	100	150	V	
Maximum RMS Voltage	V _{RMS}	14	21	28	35	42	56	70	105	V	
Maximum DC Blocking Voltage	V _{DC}	20	30	40	50	60	80	100	150	V	
Maximum Average Forward Current .375" (9.5mm) lead length at T _c =100°C	I _{AV}	8								A	
Peak Forward Surge Current :8.3ms single half sine-wave superimposed on rated load(JEDEC method)	I _{FSM}	150								A	
Maximum Forward Voltage at 8.0A	V _F	0.55			0.75		0.85		0.92	V	
Maximum DC Reverse Current TA=25°C at Rated DC Blocking Voltage TA=100°C	I _R	0.5				50					mA
Typical Thermal Resistance	R _{θJC}	6								°C / W	
Operating Junction Temperature Rang	T _J	-50 to +125								°C	
Storage Temperature Rang	T _J ,T _{STG}	-50 to +150								°C	

NOTES:

Both Bonding and Chip structure are available.



RATING AND CHARACTERISTIC CURVES

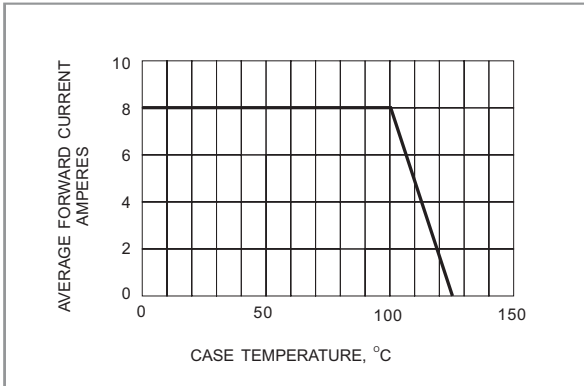


Fig.1- FORWARD CURRENT DERATING CURVE

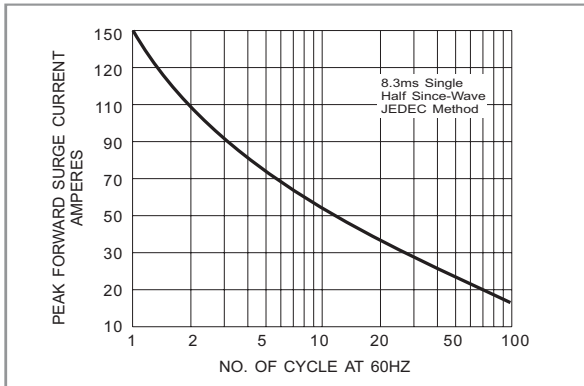


Fig.2- MAXIMUM NON-REPETITIVE SURGE CURRENT

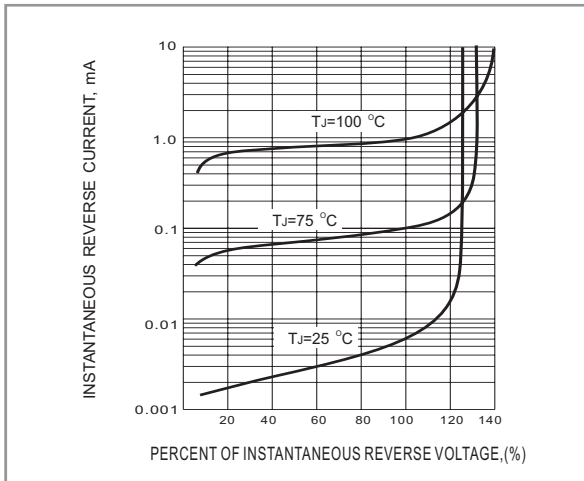


Fig.3- TYPICAL REVERSE CHARACTERISTICS

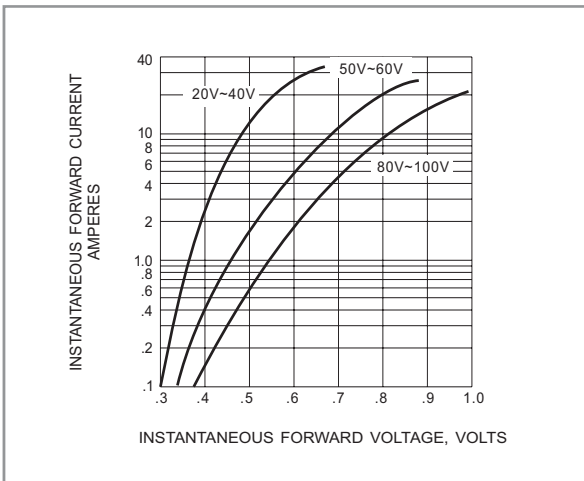


Fig.4- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS